REMARKS

Claim 44 has been amended to call for a second bond pad comprising a masked nickel coated metal, the second bond pad without a gold coating. Thus, the intermediate structure of claim 44 does not have a gold coating on the second bond pad at the time of masking.

A gold film 23 is on Haji's (JP PAT 11-067957) electrode 14 when the electrode 14 is encased by the molded resin 19. [0016]. Thus, Haji does not teach or suggest every limitation of amended claim 44.

Claim 37 has been amended to call for a support structure having parallel surfaces, a second bond pad on one parallel surface of said support structure, and a chip on another parallel surface of the support structure, the chip and the second bond pad linked by an electrically conductive element.

All of the figures in Haji show a chip with wires for bonding to the same surface of the substrate that the chip is located on. In contrast, the device of claim 37 has a bond pad on one surface of a support substrate, a chip on another parallel surface of the support structure, the chip and bond pad linked by an electrically conductive element, which in some embodiments is a gold wire.

As all of the elements of amended claim 37 are not taught or suggested by Haji, claim 37 and claims dependent thereon are believed to be patentable. Under a similar analysis, new claims 50-60 are also believed to be patentable.

In view of the amendments and remarks herein, the application is believed to be in condition for allowance. The examiner's prompt action in accordance therewith is respectfully requested. The commissioner is authorized to charge any additional fees, including extension of time fees, or credit any overpayment to Deposit Account No. 20-1504 (MCT.0046C1US).

Respectfully submitted,

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